

DUAL GAUGE LEADFRAME

ABSTRACT OF THE INVENTION

A leadframe (20) for a semiconductor device includes a first leadframe portion (12) having a perimeter that defines a cavity (16) and a plurality of leads (14) extending inwardly from the perimeter and a first thickness. A second leadframe portion (18) is attached to the first leadframe portion (16). The second leadframe portion (18) has a die paddle (20) received within the cavity (16) of the first leadframe portion (12). The second leadframe portion (18) has a second thickness that is greater than a thickness of the first leadframe portion (12). Such a dual gauge leadframe is suitable especially for high power devices in which the die paddle acts as a heat sink.